

ABSTRACT OF THE DISCLOSURE

In a circuit module, an insulation layer is formed on a first or second surface of a circuit substrate such that it substantially entirely covers the first or second surface, and
5 a first or second flip chip component is embedded in the insulation layer. Since the first and second flip chip components are thus distributed on the first and second surfaces of the circuit substrate, a reduction in size can be achieved. The flip chip component located on the side opposite to the embedded flip chip
10 component can be mounted using an exposed surface of the insulation layer as a datum. The mounting position can therefore be accurate to allow mounting with high accuracy.